



MITSUBISHI GAS CHEMICAL COMPANY, INC.

March 27, 2006

Decision to end production of multi-purpose epoxy resin copper clad laminate and other products

Mitsubishi Gas Chemical Company, Inc. ("MGC") today announced that, as of the end of December 2006, it will halt the production and sale of multi-purpose epoxy resin copper clad laminate, prepregs, and mass laminations which utilize these products.

Until now Mitsubishi Gas Chemical has developed its printed circuit board business with BT resin copper clad laminate and epoxy resin copper clad laminate at its center. In recent years, however, the sales ratio for multi-purpose epoxy resin copper clad laminates has been decreasing steadily. At the same time, there has been increasing demand for high performance products such as high performance epoxy copper clad laminates for high count layer boards, which are used in BT resin copper clad laminates and communications and information equipment—products that hold a high share of the semi-conductor packaging materials market.

In April 2005, MGC took measures to increase production of multi-purpose epoxy resins, but given the notable growth in demand for high performance products and the expectation of further expansion of this market, MGC has resolved to instead concentrate on high performance products. The Company intends to use the increased capacity arising from the cessation of multi-purpose product production to maintain a stable supply of high performance products.

1. Products to be discontinued

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|------------------------------------------------------------|-----------------------------------------------------------------------------------------|
| 1. CCL-E170 | Glass cloth epoxy resin copper clad laminate (FR-4) |
| 2. GEL-170 | Glass cloth epoxy resin unclad laminate (FR-4) |
| 3. CCL-E145 | Glass composite epoxy resin laminate (CEM-3) |
| 4. GEP-145 | Glass composite epoxy resin unclad laminate (CEM-3) |
| 5. CCL-EL170/GEPL-170 | Glass cloth epoxy resin copper clad laminates and prepregs for multi-layer board (FR-4) |
| 6. CCL-EL150/GEPL-150 | Glass cloth halogen free epoxy resin copper clad laminate and prepreg (FR-4) |
| 7. Mass laminations using the above laminate and prepregs. | |

2. Schedule for discontinuation of production

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| 1. Final orders to be taken | End November 2006 |
| 2. Final shipments | End December 2006 |

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